



UNIVERSITI PUTRA MALAYSIA

**DEVELOPMENT OF SOFTWARE SYSTEM FOR DETECTING
DEFECTIVE SYMBOL ON IC CHIP USING MATROX IMAGING
LIBRARY**

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**Thesis Submitted to the School of Graduate Studies, Universiti Putra Malaysia, in
Fulfilment of the Requirements for the Degree of Master of Science**

March 2004

Dedicated to my parents,
Muhidan Mohd Natar and Fatimah Osman

Abstract of thesis presented to the Senate of Universiti Putra Malaysia in fulfillment of the requirement for the degree of Master of Science

**DEVELOPMENT OF SOFTWARE SYSTEM FOR DETECTING DEFECTIVE
SYMBOL ON INTEGRATED CIRCUIT CHIP USING MATROX IMAGING
LIBRARY**

By

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March 2004

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In semiconductor fabrication process, symbol or label inspection is one of the main processes that needs to be considered seriously. Errors may occur during the printing process of label or name on the integrated circuit chip (IC). If this occurs, the IC chip may have a wrong name. This will affect the credibility of the company who produces the IC chips. The problem mentioned above can be solved by providing a reliable detection system that is able to detect the errors printed on the IC chip.

The symbol detection system that currently being implemented by the semiconductor industry suffers from overkill and escapes problems. This project presents the development of a software system, which is capable of detecting the defective characters printed on the IC chip using Active Matrox Imaging Library Release 7. The proposed

system has an adjustable reading level that can solve the overkilled and escaped problems. It consists of a graphical user interface module, an inference engine, an image database, an ActiveMIL ActiveX control module, a Matrox Imaging Library module, an input image, and an output image. The proposed system is written in Visual Basic version 6 and it is interfaced with Active Matrox Imaging Library.

The proposed system also has learning capability. It can store up to two different IC images at one time. The system was designed for off-line operation. The test results demonstrated that the proposed system performs according to its functions. It achieves 100% detection rate.

Abstrak tesis yang dikemukakan kepada Senat Universiti Putra Malaysia sebagai memenuhi keperluan untuk ijazah Master Sains

**MEMBINA PROGRAM SISTEM PERISIAN UNTUK MENGESAN
KESALAHAN SIMBOL PADA CIP LITAR BERSEPADU DENGAN
MENGUNAKAN “MATROX IMAGING LIBRARY”**

Oleh

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Pemeriksaan label atau symbol pada cip litar bersepadu merupakan satu process penting yang perlu dititikberatkan di dalam proses fabrikasi semikonduktor. Sepanjang proses fabrikasi terdapat kemungkinan berlaku kesilapan mencetak label atau symbol pada cip litar bersepadu. Kesilapan mencetak pada litar bersepadu akan menyebabkan cip berkenaan mempunyai nama yang salah dan ini akan memberi kesan kepada kredibiliti syarikat pengeluar cip tersebut. Walaubagaimanapun, masalah ini dapat di atasi dengan menggunakan sistem pengesan yang dibina untuk mengesan kesalahan melabel atau mencetak simbol pada cip litar bersepadu.

Sistem pengesanan simbol yang sedia ada di dalam pasaran industri semikonduktor sekarang tidak bergitu berkesan kerana sistem tersebut tidak dapat membezakan di antara cip litar bersepadu yang boleh diterima pakai dengan cip yang rosak semasa

proses pengesanan. Projek ini mempersembahkan pembinaan sistem perisian yang mampu mengesan kesalahan mencetak simbol pada cip litar bersepadu dengan menggunakan 'ActiveMIL Release 7'.

Di dalam sistem cadangan ini terdapat kesesuaian tahap bacaan bagi sesuatu imej litar bersepadu, di mana kesesuaian ini dapat menyelesaikan masalah untuk membezakan di antara cip litar bersepadu yang boleh diterima pakai atau tidak semasa process pengesanan. Sistem cadangan ini mengandungi hubungan antara grafik dengan pengguna, kewarasan enjin, butiran maklumat imej, modul kawalan 'ActiveMIL ActiveX', modul 'MIL', bahagian kemasukan imej dan bahagian keluaran imej. Sistem cadangan ini ditulis dalam 'Visual Basic Version 6' dan ia dihubungkan dan disambungkan dengan 'ActiveMIL'.

Sistem ini juga mengandungi kebolehan untuk memperolehi maklumat daripada proses pembelajaran. Dua jenis imej cip litar bersepadu yang berbeza untuk dianalisis boleh disimpan pada masa yang sama. Keputusan ujian menunjukkan bahawa sistem yang dibina ini dapat melaksanakan proses pengesanan simbol pada cip litar bersepadu dengan efektif dan sistem ini boleh mencapai kadar pengesanan sebanyak 100%.

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CHAPTER 1

INTRODUCTION

1.1 Introduction

The character recognition system has many applications. These include license car plate number verification (Yamanguchi, et al., 1999), verification of postcodes in handwritten and hand-printed addresses (Kabir, et al., 1990), money transfer forms and cheques used by banks (Miletzki, 1997), etc. In semiconductor fabrication process, symbol or marking inspection is one of the main processes that needs to be considered seriously.

Symbol or marking inspection algorithms have changed very little since their introduction onto the semiconductor industry in the late 80's. On the contrary, customers' quality requirements have increased many folds. They will no longer tolerate the packing errors such as wrong symbol printed on the IC, unclear characters on IC, etc. At the same time, manufacturers face the problems of overkilled or escaped IC chip. The current inspection system cannot solve the overkilled and escaped problems. Overkilled event occurs when the inspection system rejects the IC, which has a minor error printed on the IC chip. The characters printed on the IC chip can still be read with bare human eyes. However, if this problem is not rectified, the manufacturer will lose its profits. Meanwhile, the escaped event will occur when the inspection system is unable to detect the error printed on the IC chips. This problem will cause the manufacturer to lose its customers because the manufacturer provides wrong or defective IC chips.